

TITLE OF THE INVENTION: SEMICONDUCTOR PACKAGES WITH A BRIDGE SEMICONDUCTOR DIE AND METHODS FOR FORMING THE SAME

Abstract

A semiconductor package comprises: a package substrate having a first region, a second region and an opening between the first and second regions; a first semiconductor die mounted on the first region via a first set of solder bumps and having a first overhanging portion above the opening; a second semiconductor die mounted on the second region via a second set of solder bumps and having a second overhanging portion above the opening; a bridge semiconductor die mounted onto respective back surfaces of the first overhanging portion and the second overhanging portion via a third set of solder bumps, wherein the bridge semiconductor die is aligned with the opening; and an underfill layer filled between both of the first and second semiconductor dice and both of the package substrate and the bridge semiconductor die.

[Fig. 1]